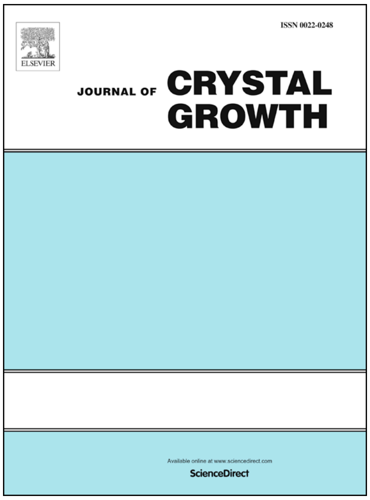

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T. Jain, H.K. Lin, C.W. Lan

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T. Jain, H. K. Lin, C.W. Lan*

Department of Chemical Engineering, National Taiwan University, Taipei, 10617, Taiwan

*Corresponding author: cwlan@ntu.edu.tw; Tel.: 886-2-2363-3917

Fax: 886-2-2363-3917